



Customer Information Notification

202003032I

Issue Date: 11-Apr-2020
Effective Date: 12-Apr-2020

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This notice is NXP Company Proprietary.



QUALITY

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other - Data Sheet Update - Corrections and Clarifications | | | |

MC33772B Data Sheet Update to Rev 6.0 (Corrections and Technical Clarifications)

Description

NXP Semiconductors announces the data sheet update to revision 6.0 for the MC33772B Battery Cell Controller IC devices associated with this notification. The revision history included in the updated document provides a detailed description of the changes. Changes are summarized below.

Data Sheet Changes:

1. Table 4: Correct typo in communication type corresponding to given values (typo correction)
2. Table 7: Add missing footnote call on VCVFV and VLEAK line. Footnote existed but was not called on these lines (typo correction)
3. Table 7, Footnote 18: Correct document reference name/number (informative)
4. Table 9: Reword to clarify communication behavior in Normal, Diagnostic, Idle and Sleep mode (description improvement)
5. Section 9.4.2, Section 12.1 and Tables 64, 65 and 66: Clarify note about Vana fault (description improvement)
6. Section 9.13: Add note regarding current sense in sleep mode and cyclic acquisition (additional recommendations)
7. Section 9.17: Clarify CBx_CFG bits behavior (description improvement)
8. Section 9.18: Add step in "Cell balance fault diagnostics" (procedure modification, already implemented in the Safety Manual)
9. Section 11: Reformat register map (description improvement)
10. Section 11: Clarify status for reserved and not used bits (description improvement)
11. Table 92: Update list of "reserved" registers (informative)
12. Section 13.2.3: Correct maximum VPWR voltage to sustain hot plug (informative)
13. Section 13.2.1: Add paragraph regarding CTREF variations (optional application improvement - optional diodes - no system impact)
14. Table 102: Correct CTPL value (EVB hardware change, no system impact)

15. Other minor typo corrections throughout the document

** Documentation change only for customer clarifications - absolutely no changes to the device / product **

New MC33772B rev 6.0 data sheet may be obtained from the secure DocStore portal:

<https://www.docstore.nxp.com/products?path=/content/docstore/product-hierarchy/Automotive-Battery-Management/MC33771--MC33772--MC33664/Datasheet&folderuuid=10722735-c3a3-47dd-a794-8eec20db8c66>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

The data sheet has been updated to correct errors, and provide additional technical clarification on some device features, as well as on the register map.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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<u>Affected OPN</u>	<u>Affected 12NC</u>
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MC33772BSP1AE	935358985557
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MC33772BTC0AE	935363206557
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MC33772BTP1AE	935359123557
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